

SDF701AB 5 MIN EPOXY

Technical datasheet



Application

Epoxy resin 701AB is an epoxy resin adhesive cured at normal temperature and low temperature. It is easy to operate, fast curing, strong adhesion, and can be cured by heating. It is specially used for metal bonding, electronic product bonding, hard material bonding and mold infusion, as well as other electronic parts insulation, moisture-proof potting, privacy masking, etc.

Properties before hardening

	Epoxy Resin 701A	Hardener 701B	Mixed Adhesive
Appearance	Clear	Light yellow	
Specific gravity	1.15	1.05	
Viscosity at 25°C (Pa.s)	8000-12000	5500-8500	
Mixing Ratio (weight)	100	100	
Pot life at 25°C (100gr)			2min(100gr)

Method of use

Working environment: Please keep the plastic container clean. The A and B components must be accurately weighed according to the weight ratio and accurately weighed. Stir thoroughly clockwise along the inner wall of the container and let it stand for 3-5 minutes before using.

Adjust the amount of glue according to the operating time and dosage to avoid waste. When the temperature is lower than 15 °C, please preheat A glue to 30 °C before adjusting the glue, which is easy to operate (A glue will thicken when the temperature is low); After use, the bucket lid must be sealed to avoid product scrap due to moisture absorption.

When the relative humidity is greater than 85%, the surface of the cured product easily absorbs moisture in the air and forms a white mist. Therefore, when the relative humidity is greater than 85%, it is not suitable for normal temperature curing. It is recommended to use temperature curing.

Properties after hardening

Hardness	Shore D	<85
Withstand voltage	KV/mm	22
Bending strength	Kg/mm ²	24
Volume resistance	Ohm3	1x10 ¹⁵
Surface resistance	Ohmm ²	5X10 ¹⁵
Thermal conductivity	W/M.K	0.61
Electricity loss	1KHZ	0.42
Heat distortion temperature	°C	140
Water absorption	%	<0.15
Compressive strength	Kg/mm ²	12.5

The above performance data are typical data measured in a laboratory environment with a temperature of 25 °C and a humidity of 70%, and are for customer reference only.